ELECTROPLATING APPARATUSES AND METHODS EMPLOYING LIQUID PARTICLE COUNTER MODULES

ABSTRACT

Disclosed herein are electroplating apparatuses for electroplating metal onto a semiconductor wafer which may include an electroplating cell, an electrolyte circulation system connected to the cell for circulating electrolyte to and from the cell, first and second sampling ports for taking first and second sample of electrolyte at first and second locations in the apparatus, and one or more liquid particle counter modules, connected to the first and second sampling ports, for measuring particle concentration in the electrolyte. Also disclosed herein are methods for reducing particle concentration in an electrolyte present in an electroplating apparatus which may include determining an approximate particle concentration using a liquid particle counter module and modifying the operation of the electroplating apparatus to reduce particle concentration in the electrolyte.

Fig. 1



